Preferred Device

SWITCHMODE Power Rectifier

DPAK Surface Mount Package

This SWITCHMODE power rectifier which uses the Schottky Barrier principle with a proprietary barrier metal, is designed for use as output rectifiers, free wheeling, protection and steering diodes in switching power supplies, inverters and other inductive switching circuits.

Features

- Low Forward Voltage
- 150°C Operating Junction Temperature
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Compact Size
- Lead Formed for Surface Mount
- Pb–Free Packages are Available

Mechanical Characteristics

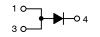
- Case: Epoxy, Molded
- Weight: 0.4 Gram (Approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Shipped 75 Units Per Plastic Tube
- Available in 16 mm Tape and Reel, 2500 Units Per 13 in Reel, by Adding a "T4" Suffix to the Part Number
- ESD Rating: Machine Model = C (> 400 V) Human Body Model = 3B (> 8000 V)



ON Semiconductor®

http://onsemi.com

SCHOTTKY BARRIER RECTIFIER 8.0 AMPERES, 35 VOLTS



MARKING DIAGRAM



| Y | = Year |
|----|------------------|
| WW | = Work Week |
| G | = Pb-Free Device |

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|-------------|-------------------|-----------------------|
| MBRD835L | DPAK | 75 Units/Rail |
| MBRD835LG | DPAK (Pb-Free) | 75 Units/Rail |
| MBRD835LT4 | DPAK | 2500/Tape & Reel |
| MBRD835LT4G | DPAK (Pb-Free) | 2500/Tape & Reel |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

MAXIMUM RATINGS

| Rating | Symbol | Value | Unit |
|---|--|-------------|------|
| Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage | V _{RRM} V _{RWM} V _R | 35 | V |
| Average Rectified Forward Current (At Rated V_R , $T_C = 88^{\circ}C$) | I _{F(AV)} | 8.0 | A |
| Peak Repetitive Forward Current (At Rated V _R , Square Wave, 20 kHz, $T_C = 80^{\circ}C$) | I _{FRM} | 16 | A |
| Non-Repetitive Peak Surge Current (Surge applied at rated load conditions, halfwave, single phase, 60 Hz) | I _{FSM} | 75 | A |
| Repetitive Avalanche Current (Current Decaying Linearly to Zero in 1 $\mu s,$ Frequency Limited by T_{Jmax}) | I _{AR} | 2.0 | A |
| Storage / Operating Case Temperature | T _{stg} | -65 to +150 | °C |
| Operating Junction Temperature (Note 1) | TJ | -65 to +150 | °C |
| Voltage Rate of Change (Rated V _R) | dv/dt | 10,000 | V/μs |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

THERMAL CHARACTERISTICS

| Rating | Symbol | Value | Unit |
|---|-----------------|-------|------|
| Thermal Resistance – Junction-to-Case | $R_{\theta JC}$ | 2.8 | °C/W |
| Thermal Resistance – Junction-to-Ambient (Note 2) | R_{\thetaJA} | 80 | °C/W |

ELECTRICAL CHARACTERISTICS

| Maximum Instantaneous Forward Voltage (Note 3) | (i _F = 8 Amps, T _C = +25°C) (i _F = 8 Amps, T _C = +125°C) | V _F | 0.51 0.41 | V |
|--|---|----------------|--------------|----|
| Maximum Instantaneous Reverse Current (Note 3) | (Rated dc Voltage, $T_C = +25^{\circ}C$) (Rated dc Voltage, $T_C = +100^{\circ}C$) | Ι _R | 1.4 35 | mA |

1. The heat generated must be less than the thermal conductivity from Junction-to-Ambient: $dP_D/dT_J < 1/R_{\theta JA}$. 2. Rating applies when surface mounted on the minimum pad size recommended. 3. Pulse Test: Pulse Width = 300 µs, Duty Cycle ≤ 2%.

TYPICAL CHARACTERISTICS

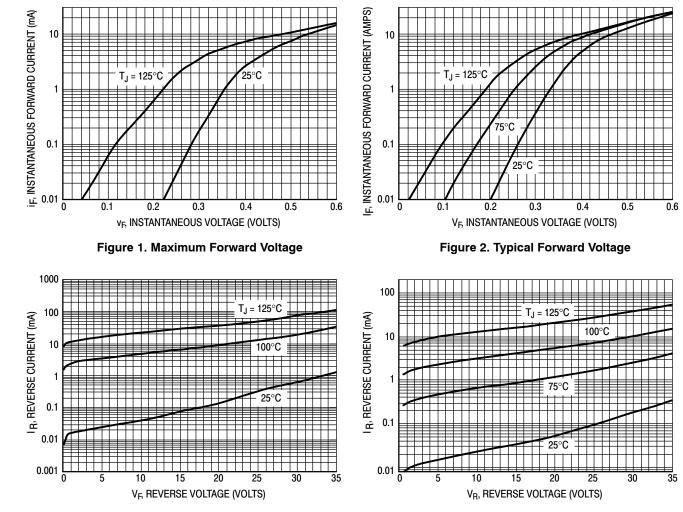
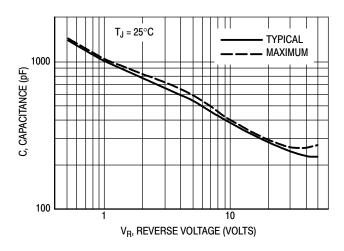


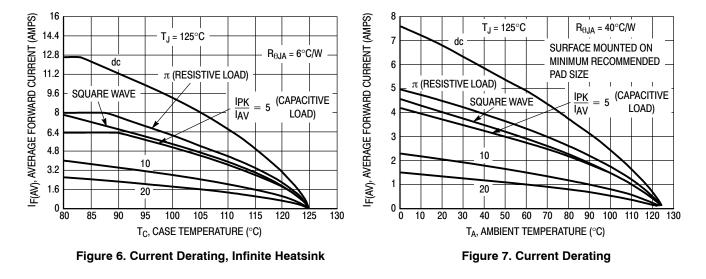
Figure 3. Maximum Reverse Current

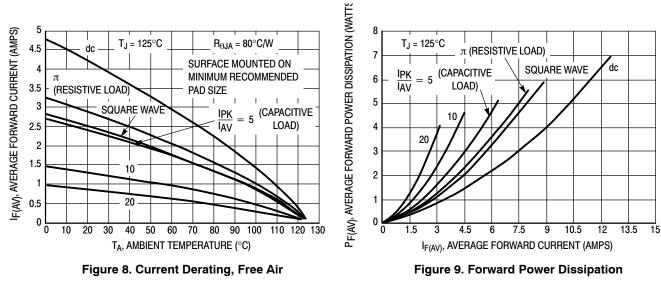
Figure 4. Typical Reverse Current

TYPICAL CHARACTERISTICS





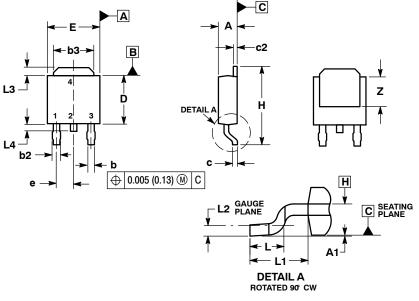




PACKAGE DIMENSIONS

DPAK (SINGLE GAUGE) CASE 369C-01

ISSUE D

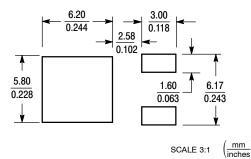


NOTES:

- 1. DIMENSIONING AND TOLERANCING PER ASME
- Y14.5M, 1994. 2. CONTROLLING DIMENSION: INCHES.
- 3. THERMAL PAD CONTOUR OPTIONAL WITHIN
- DIMENSIONS b3, L3 and Z. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL
- NOT EXCEED 0.006 INCHES PER SIDE. 5. DIMENSIONS D AND E ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY. 6. DATUMS A AND B ARE DETERMINED AT DATUM
- PLANE H.

| | INCHES | | MILLIN | IETERS | |
|-----|-----------|-------|----------|----------|--|
| DIM | MIN | MAX | MIN | MAX | |
| Α | 0.086 | 0.094 | 2.18 | 2.38 | |
| A1 | 0.000 | 0.005 | 0.00 | 0.13 | |
| b | 0.025 | 0.035 | 0.63 | 0.89 | |
| b2 | 0.030 | 0.045 | 0.76 | 1.14 | |
| b3 | 0.180 | 0.215 | 4.57 | 5.46 | |
| с | 0.018 | 0.024 | 0.46 | 0.61 | |
| c2 | 0.018 | 0.024 | 0.46 | 0.61 | |
| D | 0.235 | 0.245 | 5.97 | 6.22 | |
| E | 0.250 | 0.265 | 6.35 | 6.73 | |
| е | 0.090 BSC | | 2.29 BSC | | |
| Н | 0.370 | 0.410 | 9.40 | 10.41 | |
| L | 0.055 | 0.070 | 1.40 | 1.78 | |
| L1 | 0.108 REF | | 2.74 REF | | |
| L2 | 0.020 BSC | | 0.51 | 0.51 BSC | |
| L3 | 0.035 | 0.050 | 0.89 | 1.27 | |
| L4 | | 0.040 | | 1.01 | |
| Z | 0.155 | | 3.93 | | |

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

ON Semiconductor and 💷 are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800-282-9855 Toll Free USA/Canada Europe, Middle East and Africa Technical Support:

Phone: 421 33 790 2910 Japan Customer Focus Center Phone: 81-3-5773-3850

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative